

Product Data Sheet

✧ DVKL5613WDBBSRG

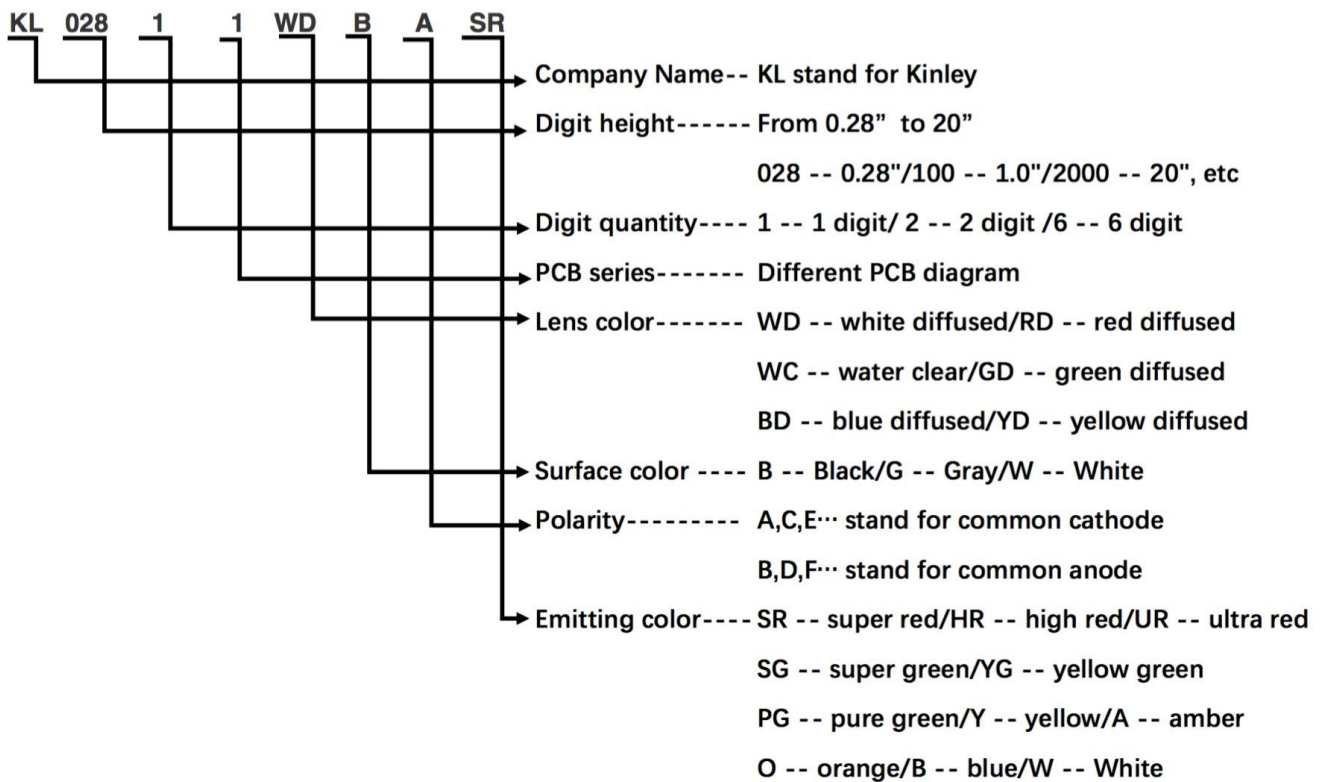
✧ Digit height: 0.56 inch (14.20mm)

✧ Digit number: 1 digit

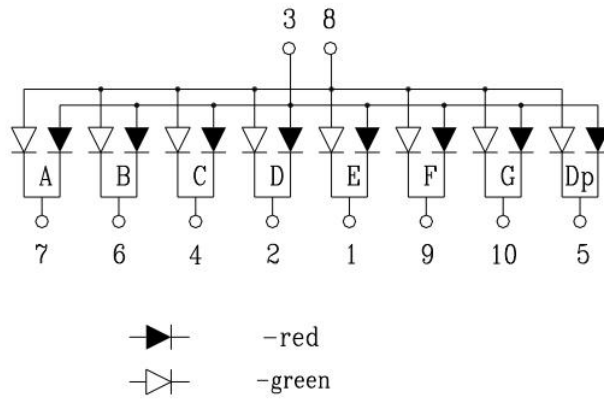
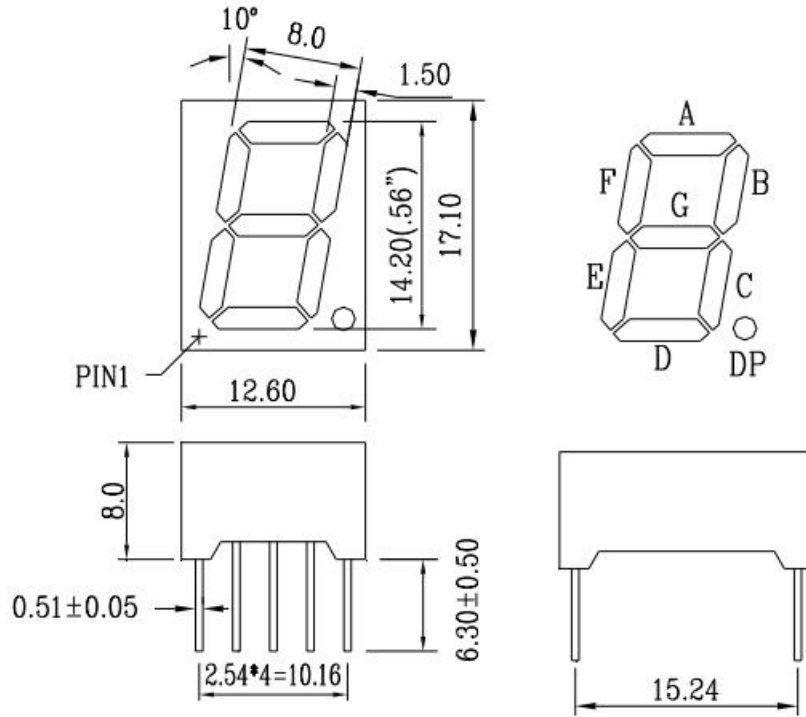
✧ Emitting color: Super red + super green

Selection Guide

Part No.	Emitting color	Wavelength	Lens color	Intensity	Polarity	Surface color
DVKL05613WDBBSRG	Super red+	620-630nm	White	110-130mcd	Common	Black
	Super green	568-573nm	diffused	50-60mcd	anode	



Dimension and Diagram



Notes:

1. Dimension in millimeter [inch], tolerance is ±0.25 [.010] and angle is ±1° unless otherwise noted.
2. Bending ≤ Length*1%.
3. The specifications characteristics and technical data described in the datasheet are subject to change without prior notice.

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Test Condition	Value		Unit
			Min	Max	
Reverse Voltage	VR	IR=30	5	—	V
Forward Current	IF	—	—	10	mA
Power Dissipation	Pd	—	—	100	mW
Pulse Current	Ipeak	Duty=0.1mS,1KHz	—	150	mA
Operating Temperature	T opr	—	-40	+85	°C
Storage Temperature	T str	—	-40	+85	°C

Electro-Optical Characteristics (Ta=25°C)

Parameter		Symbol	Min.	Typ.	Max.	Units	Condition
Forward Voltage	Per segment	VF	--	1.9	2.1	V	IF=10mA
	Per decimal point		--	1.9	2.1		
Reverse Current		IR	--	--	10	μA	VR=5V
Luminous Intensity	Per segment	IV	110	120	130	mcd	IF=10mA
	Per decimal point		50	55	60		
Peak Wavelength	Super red	λp	--	630	--	nm	IF=10mA
	Super green	λp	--	573	--	nm	
Dominant Wavelength	Super red	λd	--	625	--	nm	IF=10mA
	Super green	λd	--	571	--	nm	
Spectrum Radiation Bandwidth		Δλ	--	20	--	nm	IF=10mA

Note:

- 1.Luminous Intensity is based on the DEVETECH standards.
- 2.Pay attention about Intensity is only for one chip

Reliability test items and conditions:

The reliability of products shall be satisfied with items listed below. Confidence level:90% LTPD:10%

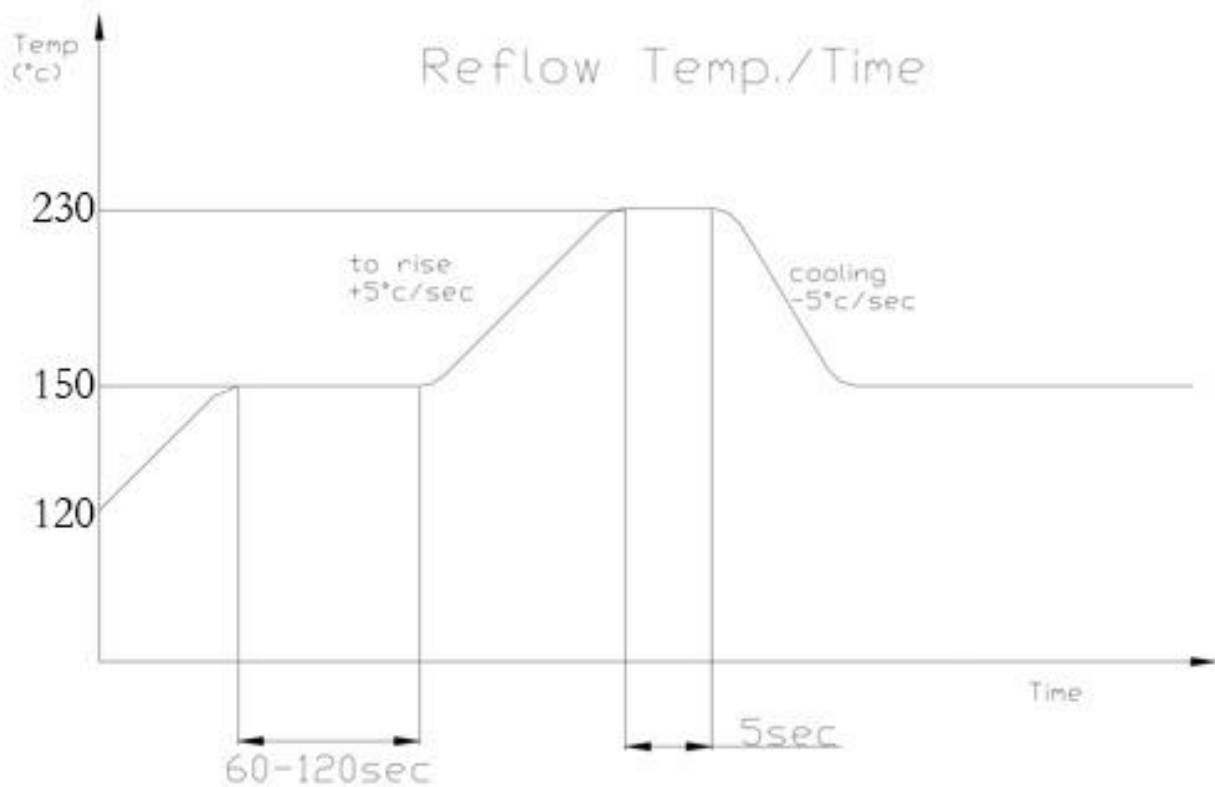
NO	Item	Test Conditions	Test Hours/Cycle	Sample Size	Failure Judgment Criteria	Ac/Re
1	Reflow Soldering	TEMP:230°C±5°C Min. 5 SEC	6 Min	22 PCS	Iv ≧ Ivt*0.5 or VF ≧ U or VF ≧ L	0/1
2	Temperature Cycle	H:+100°C 15min f 5min L:-40°C 15min	300 Cycles	22 PCS		0/1
3	Thermal Shock	H:+100°C 5min f 10 sec L:-10°C 5min	300 Cycles	22 PCS		0/1
4	High Temperature Storage	TEMP:100°C	1000 HRS	22PCS		0/1
5	Low Temperature Storage	TEMP:-40°C	1000 HRS	22 PCS		0/1
6	DC Operating Life	TEMP:25°C If=10mA	1000 HRS	22 PCS		0/1
7	High Temperature / High Humidity	85°C / 85% RH	1000 HRS	22 PCS		0/1

Note:

Ivt: The test Iv value of the chip before the reliability test

Iv: The test value of the chip that has completed the reliability test

U: Upper Specification Limit L: Lower Specification Limit

Reflow Temp. / Time :**■ Soldering Iron :**

Basic spec is $\cong 5$ sec when 230°C. If temperature is higher, time should be shorter (+10°C → -1sec).

Power dissipation of iron should be smaller than 15 W, and temperature should be controllable. Surface temperature of the device should be under 230 °C.

■ Rework :

1. Customer must finish rework within 5 sec under 230°C.
2. The head of iron can not touch copper foil.